



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01536	REV: A	SUN REV: Not In VersionControl
	TID #: TIDA-01536		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 7/28/2017 1:10:47 PM	TEXAS INSTRUMENTS	

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